ADF4210/ADF4211/ADF4212/ADF4213—SPECIFICATIONS¹

 $(V_{DD}1=V_{DD}2=3~V~\pm~10\%, 5~V~\pm~10\%; V_{DD}1, V_{DD}2\leq V_P1, V_P2\leq 6.0~V; AGND_{RF}=DGND_{RF}=AGND_{IF}=DGND_{IF}=0~V; R_{SET}=2.7~k\Omega~dBm~to~50~\Omega; T_A=T_{MIN}~to~T_{MAX}~unless~otherwise~noted.)$

| Parameter | B Version | B Chips ² | Unit | Test Conditions/Comments |
|--|-------------------------------|-------------------------------|---|--|
| RF/IF CHARACTERISTICS (3 V) | | | | |
| RF Input Frequency (RF _{IN}) | | | | See Figure 3 for Input Circuit. |
| ADF4210 | 0.1/1.2 | 0.1/1.2 | GHz min/max | Use a square wave for frequencies lower than F _{MIN} |
| ADF4211 | 0.1/2.0 | 0.1/2.0 | GHz min/max | |
| ADF4212 | 0.15/2.7 | 0.15/2.7 | GHz min/max | |
| ADF4213 | 0.2/3.0 | 0.2/3.0 | GHz min/max | |
| RF Input Sensitivity | -10/0 | -10/0 | dBm min/max | |
| IF Input Frequency (IF _{IN}) | | | | |
| ADF4210 | 60/550 | 60/550 | MHz min/max | |
| ADF4211 | 60/550 | 60/550 | MHz min/max | |
| ADF4212 | 0.06/1.0 | 0.06/1.0 | GHz min/max | |
| ADF4213 | 0.06/1.0 | 0.06/1.0 | GHz min/max | |
| VF Input Sensitivity | -10/0 | -10/0 | dBm min/max | |
| Maximum Allowable | 10/0 | 10,0 | 42111 111111 111411 | |
| Prescaler Output Frequency ³ | 165 | 165 | MHz max | |
| | | 103 | 11112 11141 | |
| REALE CHARACTERISTICS (5.17) | | | | |
| RF Input Frequency (RF _{FN}) | $(\ \)$ | | | See Figure 3 for Input Circuit. |
| ADF4210 | 0.18/1-2 | 0.18/1.2 | GHz min/max | Use a square wave for frequencies lower than F _{MIN} |
| ADF4211 | 0.18/2.0 | 0,18/2.0 | GHz/min/max | |
| ADF4212 | 0.2/2.3 | 0.2/2.3 | GHz min/max | |
| ADF4213 | 0.2/2.5 | 0.2/2.5 | GHz m/n/max | |
| RF Input Sensitivity | 5/0 | 5 /0 | dBm min/max | |
| IF Input Frequency (IF _{IN}) | , | | 1 / / | |
| ADF4210 | 100/550 | 100/550 | MHz min/max | |
| ADF4211 | 100/550 | 100/550 | MHz min/max | |
| ADF4212 | 0.1/1.0 | 0.1/1.0 | GHz min/max | |
| ADF4213 | 0.1/1.0 | 0.1/1.0 | GHz min/max | |
| IF Input Sensitivity | -5/0 | -5/0 | dBm min/max | |
| Maximum Allowable | 3,0 | 370 | 42111 111111 111411 | |
| Prescaler Output Frequency ³ | 200 | 200 | MHz max | |
| | 1 200 | 1 200 | 111111111111111111111111111111111111111 | — |
| REFIN CHARACTERISTICS | | | | See Figure 2 for Input Circuit. |
| REFIN Input Frequency | 0/115 | 0/115 | MHz min/max | For F < 5 MHz, use dc-coupled square wave |
| | | | | $(0 \text{ to } V_{DD}).$ |
| REFIN Input Sensitivity ⁴ | -5/0 | -5/0 | dBm min/max | AC-Coupled. When dc-coupled, 0 to V_{DD} max |
| | | | | (CMOS-Compatible) |
| REFIN Input Capacitance | 10 | 10 | pF max | |
| REFIN Input Current | ±100 | ±100 | μA max | |
| PHASE DETECTOR | | | | |
| Phase Detector Frequency ⁵ | 55 | 55 | MHz max | |
| Thase Detector Frequency |)) |)) | IVII IZ III ax | |
| CHARGE PUMP | | | | |
| I _{CP} Sink/Source | | | | Programmable: See Table V |
| High Value | 5 | 5 | mA typ | With $R_{SET} = 2.7 \text{ k}\Omega$ |
| Low Value | 625 | 625 | μA typ | 021 |
| Absolute Accuracy | 3 | 3 | % typ | With $R_{SET} = 2.7 \text{ k}\Omega$ |
| R _{SET} Range | 1.5/5.6 | 1.5/5.6 | $k\Omega$, min/max | SE1 |
| I _{CP} Three-State Leakage Current | 1 | 1 | nA typ | |
| Sink and Source Current Matching | 2 | 2 | % typ | $0.5 \text{ V} \le \text{V}_{\text{CP}} \le \text{V}_{\text{P}} - 0.5 \text{ V}$ |
| I _{CP} vs. V _{CP} | 2 | 2 | % typ | $0.5 \text{ V} \le \text{V}_{\text{CP}} \le \text{V}_{\text{P}} - 0.5 \text{ V}$ |
| I _{CP} vs. V _{CP} | 2 | 2 | % typ | $V_{CP} = V_P/2$ |
| | | + | / · · · · · · · · · · · · · · · · · · · | · Gr • 17/2 |
| LOGIC INPUTS | | | | |
| V _{INH} , Input High Voltage | $0.8 \times \mathrm{DV_{DD}}$ | $0.8 \times \mathrm{DV_{DD}}$ | V min | |
| V _{INL} , Input Low Voltage | $0.2 \times \mathrm{DV_{DD}}$ | $0.2 \times \mathrm{DV_{DD}}$ | V max | |
| I _{INH} /I _{INL} , Input Current | ±1 | ±1 | μA max | |
| C _{IN} , Input Capacitance | 10 | 10 | pF max | |
| LOGIC OUTPUTS | | | | |
| V _{OH} , Output High Voltage | $DV_{DD} - 0.4$ | $DV_{DD} - 0.4$ | V min | I _{OH} = 500 μA |
| V_{OL} , Output Low Voltage | | 0.4 | V max | |
| voi, Output Low voltage | 0.4 | 0.4 | v max | $I_{OL} = 500 \mu A$ |

| Parameter | B Version | B Chips ² | Unit | Test Conditions/Comments |
|--|-----------------------|--|-----------------|---|
| POWER SUPPLIES | | | | |
| $V_{DD}1$ | 2.7/5.5 | 2.7/5.5 | V min/V max | |
| $V_{\mathrm{DD}}2$ | $V_{\mathrm{DD}}1$ | $V_{\mathrm{DD}}1$ | | |
| $V_{ m P}$ | V _{DD} 1/6.0 | $V_{\rm DD}1/6.0$ | V min/V max | $V_{DD}1, V_{DD}2 \le V_{DD}1, V_{DD}2 \le 6.0 \text{ V}$ |
| $I_{\rm DD} (RF + IF)^6$ | | 22 | | |
| ADF4210 | 11.5 | 11.5 | mA max | 9.0 mA typical |
| ADF4211 | 15.0 | 15.0 | mA max | 11.0 mA typical |
| ADF4212 | 17.5 | 17.5 | mA max | 13.0 mA typical |
| ADF4213 | 20 | 20 | mA max | 15 mA typical |
| I _{DD} (RF Only) | | | | |
| ADF4210 | 6.75 | 6.75 | mA max | 5.0 mA typical |
| ADF4211 | 10 | 10 | mA max | 7.0 mA typical |
| ADF4212 | 12.5 | 12.5 | mA max | 9.0 mA typical |
| ADF4813 | 15 | 15 | mA max | 11 mA typical |
| I _{DD} (IN Only) | | | | |
| ADF4210 | 5.5 | 5.5 | mA max | 4.5 mA typical |
| ADF 421 / L | 5.5 | 5.5 | mA max | 4.5 mA typical |
| $AD_{421/2} / \bigcirc$ | 5.5 | 5.5 | mA max | 4.5 mA typical |
| ADF4213 / \ | 5.5 | 5.5 | mA max | 4.5 mA typical |
| $I_{p}(I_{p}1 + I_{p}2)$ | 1.0 | 1.0\ [| mA max | $T_A = 25^{\circ}C$, 0.55 mA typical |
| Low-Power Steep Mode | (/ | h | µA typ | ~ |
| | 1 1 | | 7 - 7 | |
| NOISE CHARACTERISTICS | \ | // / | / / | |
| ADF4213 Phase Noise Floor ⁷ | -171 | -17/1 | dBc/Hz typ | @ 25 kHz PFD Frequency |
| D1 | -184 | 164 L | dBc/Hz typ | @ 200 kHz PFD Frequency |
| Phase Noise Performance ⁸ | 0.1 | , L_ | in // | @ VCO Output |
| ADF4210/ADF4211, IF: 540 MHz Output ⁹ | -91 | -91 | dBc/Hz typ | @ 1 kHz Offset and 200 kHz PFD Frequency |
| ADF4212/ADF4213, IF: 900 MHz Output ¹⁰ | -89 | -89 | dBc/Hz typ | See Note 11 |
| ADF4210/ADF4211, RF: 900 MHz Output ¹⁰ | -89 | -89 | dBc/Hz typ | See Note 11 |
| ADF4212/ADF4213, RF: 900 MHz Output ¹⁰ | -91 | -91 | dBc/Hz typ | See Note 11 |
| ADF4211/ADF4212, RF: 1750 MHz Output ¹² | -85 | -85 | dBc/Hz typ | See Note 11 |
| ADF4211/ADF4212, RF: 1750 MHz Output ¹³ | -67 | -67 | dBc/Hz typ | @ 200 Hz Offset and 10 kHz PFD Frequency |
| ADF4212/ADF4213, RF: 2400 MHz Output ¹⁴ | -88 | -88 | dBc/Hz typ | @ 1 kHz Offset and 1 MHz PFD Frequency |
| Spurious Signals | 22/22 | 20/ 22 | | |
| ADF4210/ADF4211, IF: 540 MHz Output ⁹ | -88/-90 | -88/-90 | dB typ | @ 200 kHz/400 kHz and 200 kHz PFD Frequenc |
| ADF4212/ADF4213, IF: 900 MHz Output ¹⁰ | -90/-94 | -90/-94 | dB typ | See Note 11 |
| ADF4210/ADF4211, RF: 900 MHz Output ¹⁰ | -90/-94 | -90/-94 | dB typ | See Note 11 |
| ADF4212/ADF4213, RF: 900 MHz Output ¹⁰ | -90/-94 | -90/-94 | dB typ | See Note 11 |
| ADF4211/ADF4212, RF: 1750 MHz Output ¹² | -80/-82 | -80/-82 | dB typ | See Note 11 |
| ADF4211/ADF4212, RF: 1750 MHz Output ¹³ | -65/-70 | -65/ - 70 | dB typ | @ 10 kHz/20 kHz and 10 kHz PFD Frequency |
| ADF4212/ADF4213, RF: 2400 MHz Output ¹⁴ | -80/-82 | -80/-82 | dB typ | @ 200 kHz/400 kHz and 200 kHz PFD Frequenc |

NOTES

Specifications subject to change without notice.

REV. A -3-

¹Operating temperature range is as follows: B Version: -40°C to +85°C.

²The B Chip specifications are given as typical values.

This is the maximum operating frequency of the CMOS counters. The prescaler value should be chosen to ensure that the IF/RF input is divided down to a frequency that is less than this value.

 $^{^4}V_{DD}1 = V_{DD}2 = 3 \text{ V}$; For $V_{DD}1 = V_{DD}2 = 5 \text{ V}$, use CMOS-compatible levels, $T_A = 25^{\circ}C$.

⁵Guaranteed by design. Sample tested to ensure compliance.

 $^{^{6}{}m V_{DD}}$ = 3 V; P = 16; RF_{IN} = 900 MHz; IF_{IN} = 540 MHz, T_A = 25°C.

⁷The synthesizer phase noise floor is estimated by measuring the in-band phase noise at the output of the VCO and subtracting 20 logN (where N is the N divider value). See TPC 16.

⁸The phase noise is measured with the EVAL-ADF4210/ADF4212/ADF4213EB Evaluation Board and the HP8562E Spectrum Analyzer. The spectrum analyzer provides the REFIN for the synthesizer ($f_{REFOUT} = 10 \text{ MHz} \ @ 0 \text{ dBm}$). $^9f_{REFIN} = 10 \text{ MHz}$; $f_{PFD} = 200 \text{ kHz}$; Offset frequency = 1 kHz; $f_{IF} = 540 \text{ MHz}$; N = 2700; Loop B/W = 20 kHz.

 $^{^{10}}f_{REFIN} = 10 \text{ MHz}; f_{PFD} = 200 \text{ kHz}; \text{ Offset frequency} = 1 \text{ kHz}; f_{RF} = 900 \text{ MHz}; N = 4500; Loop B/W = 20 \text{ kHz}.$

¹¹Same conditions as listed in Note 10.

 $^{^{12}}f_{REFIN} = 10 \text{ MHz}; f_{PFD} = 200 \text{ kHz}; \text{ Offset frequency} = 1 \text{ kHz}; f_{RF} = 1750 \text{ MHz}; N = 8750; Loop B/W = 20 \text{ kHz}.$

 $^{^{13}}f_{REFIN} = 10$ MHz; $f_{PFD} = 10$ kHz; Offset frequency = 200 Hz; $f_{RF} = 1750$ MHz; N = 175000; Loop B/W = 1 kHz.

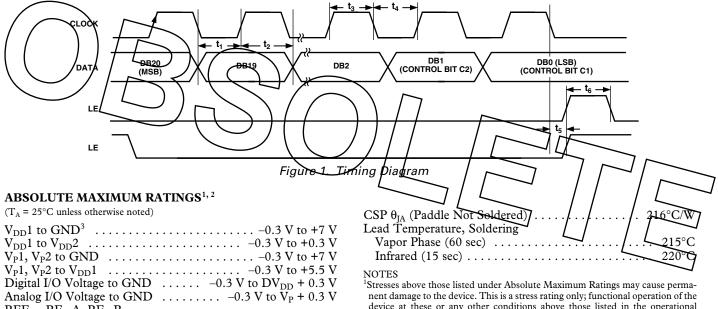
 $^{^{14}}$ f_{REFIN} = 10 MHz; f_{PFD} = 1 MHz; Offset frequency = 1 kHz; f_{RF} = 1960 MHz; N = 9800; Loop B/W = 20 kHz.

TIMING CHARACTERISTICS $(V_{DD}1 = V_{DD}2 = 3 \text{ V} \pm 10\%, 5 \text{ V} \pm 10\%; V_{DD}1, V_{DD}2 \leq V_P1, V_P2 \leq 6 \text{ V} \pm 10\%; \text{AGND}_{RF} = DGND_{RF} \\ = AGND_{IF} = DGND_{IF} = 0 \text{ V}; T_A = T_{MIN} \text{ to } T_{MAX} \text{ unless otherwise noted.})$

| Parameter | Limit at T _{MIN} to T _{MAX} (B Version) | Unit | Test Conditions/Comments |
|----------------|---|--------|---------------------------|
| t_1 | 10 | ns min | DATA to CLOCK Set-Up Time |
| t_2 | 10 | ns min | DATA to CLOCK Hold Time |
| t_3 | 25 | ns min | CLOCK High Duration |
| t_4 | 25 | ns min | CLOCK Low Duration |
| t ₅ | 10 | ns min | CLOCK to LE Set-Up Time |
| t ₆ | 20 | ns min | LE Pulsewidth |

NOTES

Guaranteed by design but not production tested. Specifications subject to change without notice.



nent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

²This device is a high-performance RF integrated circuit with an ESD rating of < 2 kV and it is ESD sensitive. Proper precautions should be taken for handling

 ${}^{3}GND = AGND = DGND = 0 \text{ V}.$

TRANSISTOR COUNT

11749 (CMOS) and 522 (Bipolar).

CAUTION_

REF_{IN}, RF_{IN}A, RF_{IN}B,

Operating Temperature Range

 $IF_{IN}A$, $IF_{IN}B$ to GND-0.3 V to VDD + 0.3 V

Industrial (B Version)-40°C to +85°C

Storage Temperature Range-65°C to +150°C

Maximum Junction Temperature 150°C TSSOP θ_{JA} Thermal Impedance 150.4°C/W

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADF4210/ADF4211/ADF4212/ADF4213 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high-energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



ORDERING GUIDE

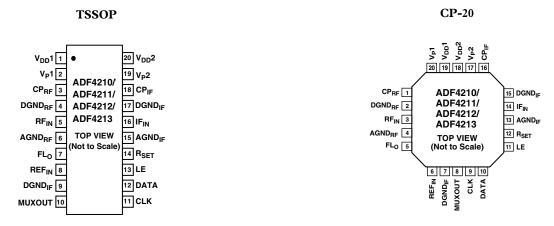
| Model | Temperature Range | Package Description | Package Option* |
|------------|-------------------|---|-----------------|
| ADF4210BRU | −40°C to +85°C | Thin Shrink Small Outline Package (TSSOP) | RU-20 |
| ADF4210BCP | −40°C to +85°C | Chip Scale Package | CP-20 |
| ADF4211BRU | −40°C to +85°C | Thin Shrink Small Outline Package (TSSOP) | RU-20 |
| ADF4211BCP | −40°C to +85°C | Chip Scale Package | CP-20 |
| ADF4212BRU | −40°C to +85°C | Thin Shrink Small Outline Package (TSSOP) | RU-20 |
| ADF4212BCP | −40°C to +85°C | Chip Scale Package | CP-20 |
| ADF4213BRU | −40°C to +85°C | Thin Shrink Small Outline Package (TSSOP) | RU-20 |
| ADF4213BCP | −40°C to +85°C | Chip Scale Package | CP-20 |

^{*}Contact the factory for chip availability.

PIN FUNCTION DESCRIPTIONS

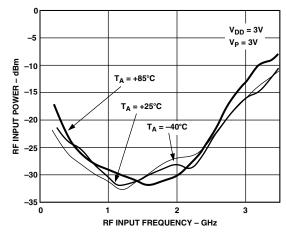
| Pin Number TSSOP | Mnemonic | Function |
|---------------------|-------------------------------|--|
| 1 | $V_{\rm DD}1$ | Power Supply for the RF Section. Decoupling capacitors to the ground plane should be placed as close as possible to this pin. $V_{\rm DD}1$ should have a value of between 2.7 V and 5.5 V. $V_{\rm DD}1$ must have the same potential as $V_{\rm DD}2$. |
| 2 | V _P 1 | Power Supply for the RF Charge Pump. This should be greater than or equal to $V_{DD}1$. In systems where $V_{DD}1$ is 3 V, it can be set to 6 V and used to drive a VCO with a tuning range up to 6 V. |
| 3 | CP_{RF} | Output from the RF Charge Pump. This is normally connected to a loop filter which drives the input to an external VCO. |
| 4 | $\mathrm{DGND}_{\mathrm{RF}}$ | Ground Pin for the RF Digital Circuitry. |
| 5 | RF _{IN} | Input to the RF Prescaler. This low level input signal is ac-coupled from the RF VCO. |
| 6 | AGND _{RF} | Ground Pin for the RF Analog Circuitry. |
| 7 | FLo | RF/IF Fastlock Mode. |
| | REFIN | Reference Input. This is a CMOS input with a nominal threshold of $V_{DD}/2$ and an equivalent input resistance of 100 k Ω . This input can be driven from a TTL or CMOS crystal oscillator. |
| (9 / / | / DGND _D) | Digital Ground for the IF Digital, Interface and Control Circuitry. |
| | MUXOUP | This multiplexer output allows either the IF/RF Lock Detect, the scaled RF, scaled IF or the scaled Reference Frequency to be accessed externally. |
| 11 | CER | Serial Clock Input. This serial clock is used to clock in the serial data to the registers. The data is latched into the 24-bit shift register on the CLK rising edge. This input is a high impedance CMOS input. |
| 12 | DATA | Serial Data Input. The serial data is loaded MSB first with the two LSBs being the control bits. This input is a high inspedance MO\$ input. |
| 13 | LE | Load Enable, CMOS Input. When LE goes high, the data stored in the shift registers is loaded into one of the four latches, the latch being selected using the control bits. |
| 14 | R _{SET} | Connecting a resistor between this pin and ground sets the maximum RF and IF charge pump output current. The nominal voltage potential at the $R_{\rm SET}$ pin is 0.66 V. The relationship between $I_{\rm CP}$ and $R_{\rm SET}$ is |
| | | $I_{CP MAX} = \frac{13.5}{R_{SET}}$ |
| | | So, with $R_{SET} = 2.7 \text{ k}\Omega$, $I_{CPMAX} = 5 \text{ mA}$ for both the RF and IF Charge Pumps. |
| 15 | $\mathrm{AGND}_{\mathrm{IF}}$ | Ground Pin for the IF Analog Circuitry. |
| 16 | IF_{IN} | Input to the RF Prescaler. This low-level input signal is ac-coupled from the IF VCO. |
| 17 | $\mathrm{DGND}_{\mathrm{IF}}$ | Ground Pin for the IF Digital, Interface, and Control Circuitry. |
| 18 | CP_{IF} | Output from the IF Charge Pump. This is normally connected to a loop filter which drives the input to an external VCO. |
| 19 | V_P2 | Power Supply for the IF Charge Pump. This should be greater than or equal to $V_{DD}2$. In systems where $V_{DD}2$ is 3 V, it can be set to 6 V and used to drive a VCO with a tuning range up to 6 V. |
| 20 | $V_{\mathrm{DD}}2$ | Power Supply for the IF, Digital and Interface Section. Decoupling capacitors to the ground plane should be placed as close as possible to this pin. $V_{DD}2$ should have a value of between 2.7 V and 5.5 V. $V_{DD}2$ must have the same potential as $V_{DD}1$. |

PIN CONFIGURATIONS

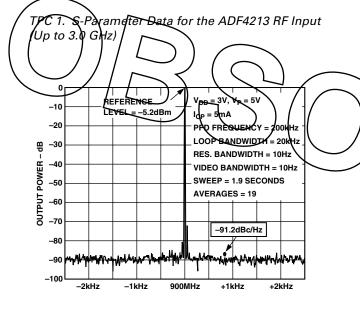


ADF4210/ADF4211/ADF4212/ADF4213-Typical Performance Characteristics

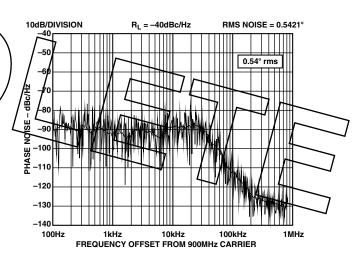
| FREQUENCY | S ₁₁ REAL | S ₁₁ IMAG | FREQUENCY | S ₁₁ REAL | S ₁₁ IMAG |
|---|---|---|---|--|--|
| 50000000.0 150000000.0 250000000.0 350000000.0 450000000.0 550000000.0 550000000.0 95000000.0 105000000.0 1150000000.0 1250000000.0 1350000000.0 1450000000.0 1550000000.0 1550000000.0 1550000000.0 1550000000.0 | 0.955683 0.956993 0.935463 0.919706 0.871631 0.838141 0.799005 0.749065 0.706770 0.630673 0.5874013 0.537311 0.505090 0.459446 0.381234 0.363150 0.330545 0.242065 0.242065 0.242065 | -0.052267 -0.112191 -0.185212 -0.252576 -0.32576 -0.350455 -0.408344 -0.471011 -0.557699 -0.602256 -0.622297 -0.642619 -0.679602 -0.679602 -0.679602 -0.679602 -0.679602 -0.679602 -0.721812 -0.679602 -0.721812 -0.673386 -0.711716 -0.723232 | 215000000.0 225000000.0 235000000.0 245000000.0 255000000.0 265000000.0 275000000.0 285000000.0 295000000.0 | 0.138086 0.102483 0.054916 0.054916 0.018475 -0.054445 -0.053716 -0.032716 -0.129543 -0.129543 -0.129543 | -0.699896 -0.704160 -0.696925 -0.6699617 -0.668965 -0.669969 -0.634725 -0.615246 -0.610398 |



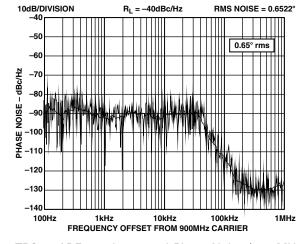
TPC 4. Input Sensitivity (ADF4213)



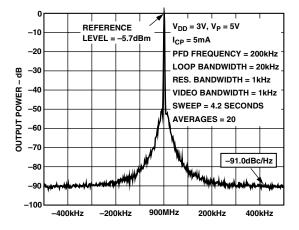
TPC 2. ADF4213 Phase Noise (900 MHz, 200 kHz, 20 kHz)



TPC 5. ADF4213 Integrated Phase Noise (900 MHz, 200 kHz, 20 kHz, Typical Lock Time: 400 μs)

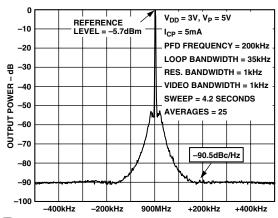


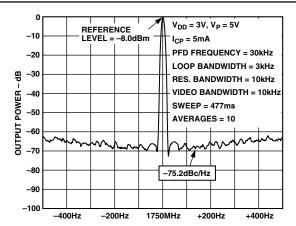
TPC 3. ADF4213 Integrated Phase Noise (900 MHz, 200 kHz, 35 kHz, Typical Lock Time: 200 µs)



TPC 6. ADF4213 Reference Spurs (900 MHz, 200 kHz, 20 kHz)

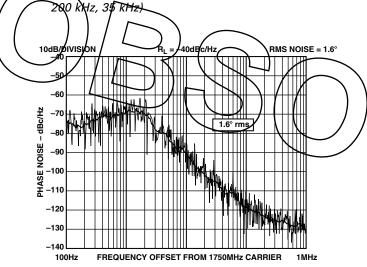
-6- REV. A

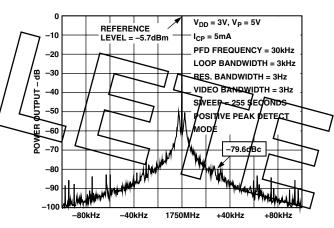




TP&7. ADF4213 Reference Spurs (900 MHz,

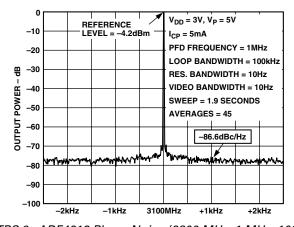
TPC 10. ADF4213 Phase Noise (1750 MHz, 30 kHz, 3 kHz)

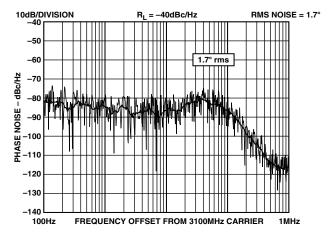




TPC 8. ADF4213 Integrated Phase Noise (1750 MHz, 30 kHz, 3 kHz)

TPC 11. ADF4213 Reference Spurs (1750 MHz, 30 kHz, 3 kHz)

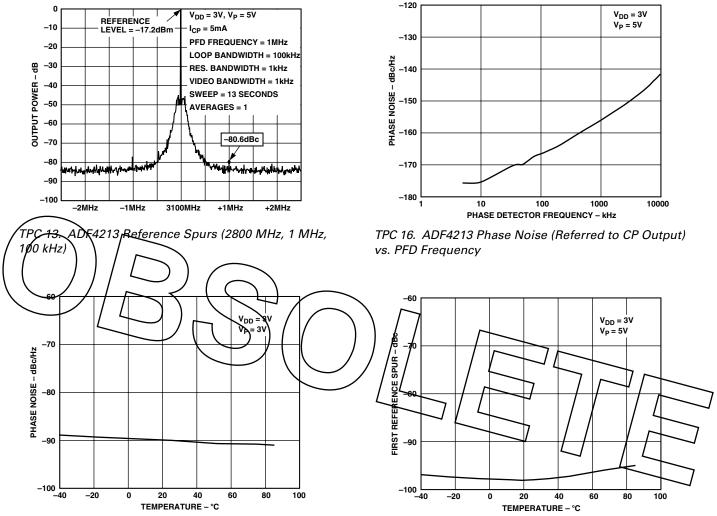




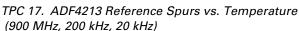
TPC 9. ADF4213 Phase Noise (2800 MHz, 1 MHz, 100 kHz)

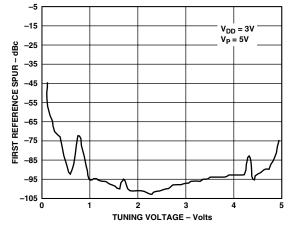
TPC 12. ADF4213 Integrated Phase Noise (2800 MHz, 1 MHz, 100 kHz)

REV. A -7-

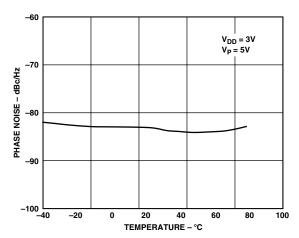


TPC 14. ADF4213 Phase Noise vs. Temperature (900 MHz, 200 kHz, 20 kHz)



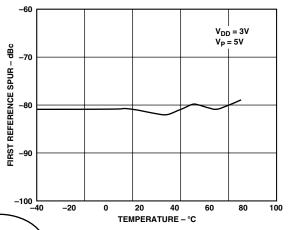


TPC 15. ADF4213 Reference Spurs (200 kHz) vs. V_{TUNE} (900 MHz, 200 kHz, 20 kHz)



TPC 18. ADF4213 Phase Noise vs. Temperature (836 MHz, 30 kHz, 3 kHz)

-8- REV. A



TPC 19. ADF4213 Reference Spurs vs. Temperature (836 MHz) 30|kHz, 3 kHz)

CIRCUM DESCRIPTION REFERENCE INPUT SECTION

The reference input stage is shown below in Figure 2. SW1 and SW2 are normally-closed switches. SW3 is normally-open. When power-down is initiated, SW3 is closed and SW1 and SW2 are opened. This ensures that there is no loading of the REF_{IN} pin on power-down.

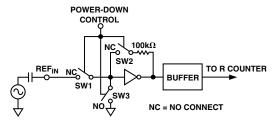


Figure 2. Reference Input Stage

RF/IF INPUT STAGE

The RF/IF input stage is shown in Figure 3. It is followed by a 2-stage limiting amplifier to generate the CML (Current Mode Logic) clock levels needed for the prescaler.

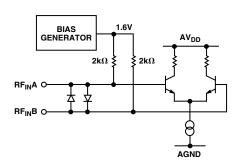


Figure 3. RF/IF Input Stage

PRESCALER (P/P + 1)

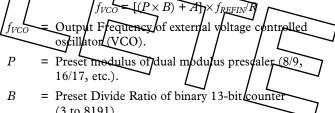
The dual modulus prescaler (P/P + 1), along with the A and B counters, enables the large division ratio, N, to be realized (N = PB + A). The dual-modulus prescaler, operating at CML levels, takes the clock from the RF/IF input stage and divides it down to a manageable frequency for the CMOS A and B counters in the RF and If sections. The prescaler in both sections is programmable. It can be set in software to 8/9, 16/17, 32/33, or 64/65. See Tables IV and VI. It is based on a synchronous 4/5 core.

RF/IF A AND B COUNTERS

The A and B CMOS counters combine with the dual modulus prescaler to allow a wide ranging division ratio in the PLL feedback counter. The counters are specified to work when the prescaler output is 200 MHz or less, when $V_{\rm DD}$ = 5 V. Typically, they will work with 250 MHz output from the prescaler. Thus, with an RF input frequency of 2.5 GHz, a prescaler value of 16/17 is valid, but a value of 8/9 is not valid.

Pulse Swallow Function

The A and B counters, in conjunction with the dual modulus prescaler make it possible to generate output frequencies which are spaced only by the Reference Frequency divided by R. The equation for the VCO frequency is as follows:



(3 to 8191).

A = Preset Divide Ratio of binary 6-bit A counter

(0 to 63). f_{REFIN} = External reference frequency oscillator.

R = Preset divide ratio of binary 15-bit programmable reference counter (1 to 32767).

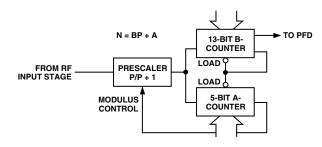


Figure 4. RF/IF A and B Counters

RF/IF COUNTER

The 15-bit RF/IF R counter allows the input reference frequency to be divided down to product the input clock to the phase frequency detector (PFD). Division ratios from 1 to 32767 are allowed.

PHASE FREQUENCY DETECTOR (PFD) AND CHARGE PUMP

The PFD takes inputs from the R counter and N counter and produces an output proportional to the phase and frequency difference between them. Figure 5 is a simplified schematic. The PFD includes a fixed-delay element that sets the width of the antibacklash pulse. This is typically 3 ns. This pulse ensures that there is no deadzone in the PFD transfer function and gives a consistent reference spur level.

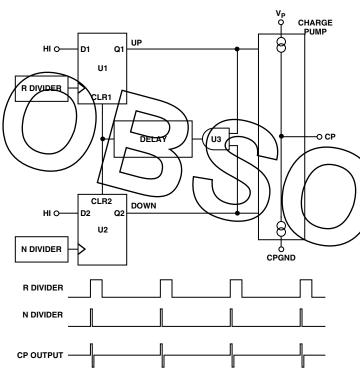


Figure 5. RF/IF PFD Simplified Schematic and Timing (In Lock)

MUXOUT AND LOCK DETECT

The output multiplexer on the ADF421x family allows the user to access various internal points on the chip. The state of MUXOUT is controlled by P3, P4, P11, and P12. See Tables III and V. Figure 6 shows the MUXOUT section in block diagram form.

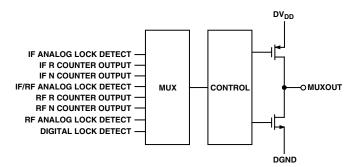


Figure 6. MUXOUT Circuit

Lock Detect

MUXOUT can be programmed for two types of lock detect: Digital Lock Detect and Analog Lock Detect. Digital Lock Detect is active high. It is set high when the phase error on three consecutive Phase Detector cycles is less than 15 ns. It will stay set high until a phase error of greater than 25 ns is detected on any subsequent PD cycle. The N-channel open-drain analog lock detect should be operated with an external pull-up resistor of 10 k Ω nominal. When lock has been detected, it is high with narrow low-going pulses.

RF/IF INPUT SHIFT REGISTER

The ADF421x family digital section includes a 24-bit input shift register, a 14-bit IF R counter and a 18-bit IF N counter, comprising a 6-bit IF A counter and a 12-bit IF B counter. Also present is a 14-bit RF R counter and an 18-bit RF N counter, comprising a 6-bit RF A counter and a 12-bit RF B counter. Data is clocked into the 24-bit shift register on each rising edge of CLK. The data is clocked in MSB first. Data is transferred from the shift register to one of four latches on the rising edge of LE. The destination latch is determined by the state of the two control bits (C2, C1) in the shift register. These are the two LSBs DB1, DB0 as shown in the timing diagram of Figure 1. The truth table for these bits is shown in Table VI. Table I shows a summary of how the latches are programmed.

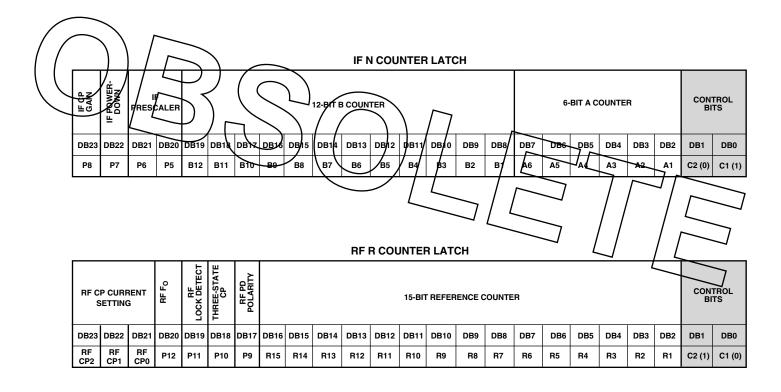
| | T | able T. C2, C1 Truth Table |
|-------|-----------|----------------------------|
| Contr | ol Bits [| |
| C2 | C1 | Data Latch |
| 0 | 0 | IF R Counter |
| 0 | 1 | IF AB Counter (A and B) |
| 1 | 0 | RF R Counter |
| 1 | 1 | RF AB Counter (A and B) |

–10– REV. A

Table II. ADF421x Family Latch Summary

IF R COUNTER LATCH

| | IF CP CURRENT SETTING LOUIS A | | | | | | | | CONTROL BITS | | | | | | | | | | | | | | |
|-----------|--|-----------|------|------|------|------|------|---|-----------------|-----|-----|-----|----|----|----|-----|-----|----|----|----|----|--------|--------|
| DB23 | DB22 | DB21 | DB20 | DB19 | DB18 | DB17 | DB16 | 316 DB15 DB14 DB13 DB12 DB11 DB10 DB9 DB8 DB7 DB6 DB5 DB4 DB3 DB2 | | | | | | | | DB1 | DB0 | | | | | | |
| IF CP2 | IF CP1 | IF CP0 | P4 | Р3 | P2 | P1 | R15 | R14 | R13 | R12 | R11 | R10 | R9 | R8 | R7 | R6 | R5 | R4 | R3 | R2 | R1 | C2 (0) | C1 (0) |



RF N COUNTER LATCH

| RF CP GAIN | RF POWER- DOWN | RI PRESC | RF ESCALER 12-BIT B COUNTER | | | | | | | | | | | 6-BIT A COUNTER | | | | | | CONTROL BITS | |
|---------------|----------------------|-------------|--------------------------------|------|--|--|--|--|--|--|--|--|------------|-----------------|------------|-----|-----|------------|--------|-----------------|--|
| DB23 | DB22 | DB21 | DB20 | DB19 | B19 DB18 DB17 DB16 DB15 DB14 DB13 DB12 DB11 DB10 DB9 DB8 | | | | | | | | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 | |
| P17 | P16 | P15 | P14 | B12 | 112 B11 B10 B9 B8 B7 B6 B5 B4 B3 B2 B1 | | | | | | | | A 6 | A 5 | A 4 | А3 | A2 | A 1 | C2 (1) | C1 (1) | |

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Table III. IF R Counter Latch Map

IF R COUNTER LATCH

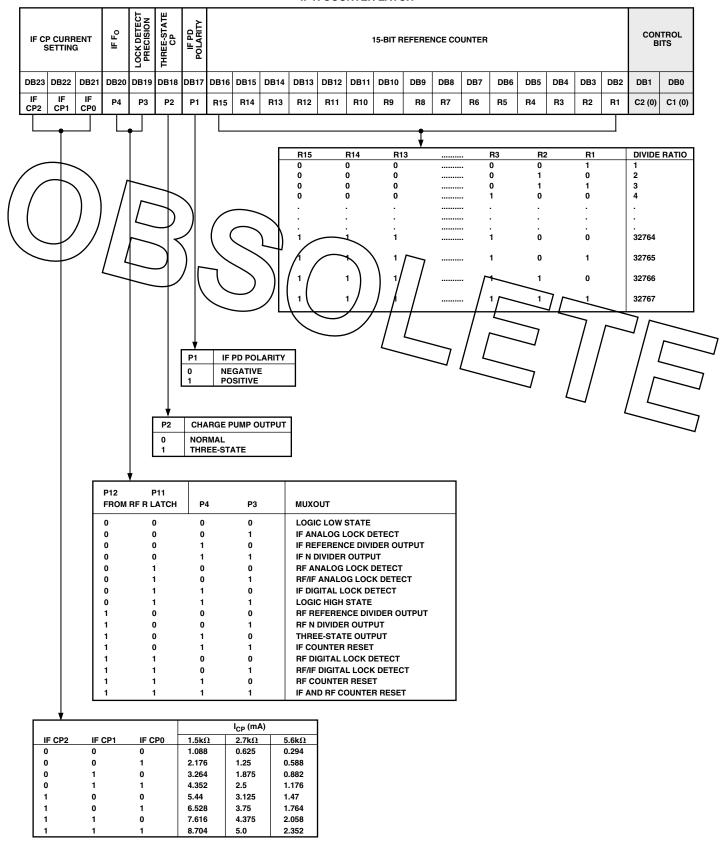
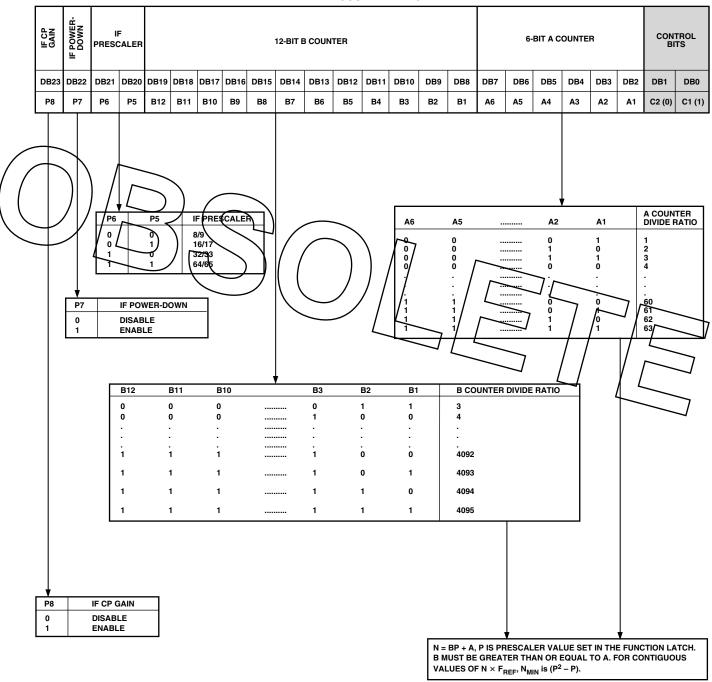


Table IV. IF N Counter Latch Map

IF N COUNTER LATCH



REV. A -13-

Table V. RF R Latch Map

RF R COUNTER LATCH

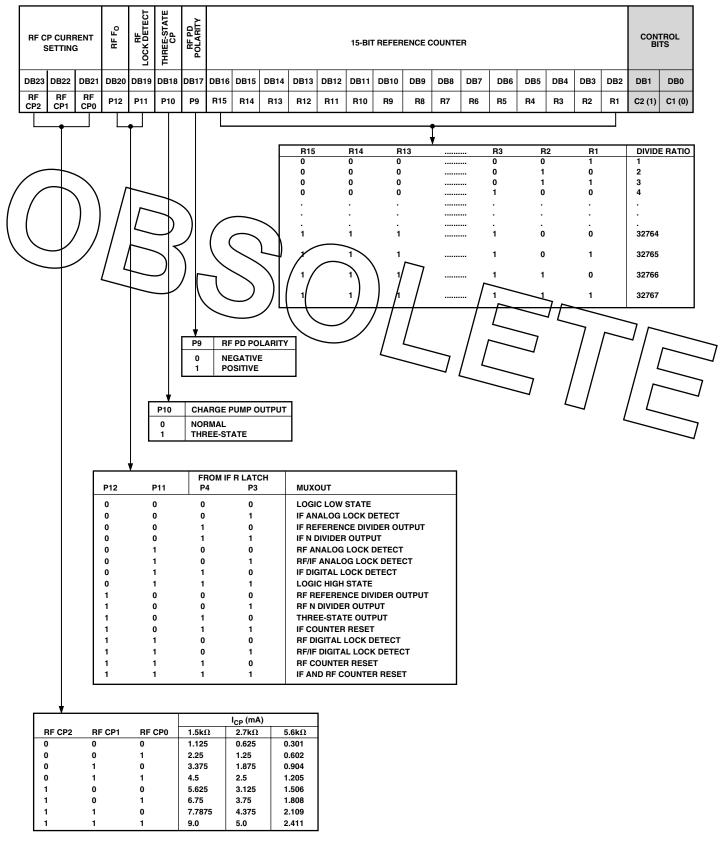
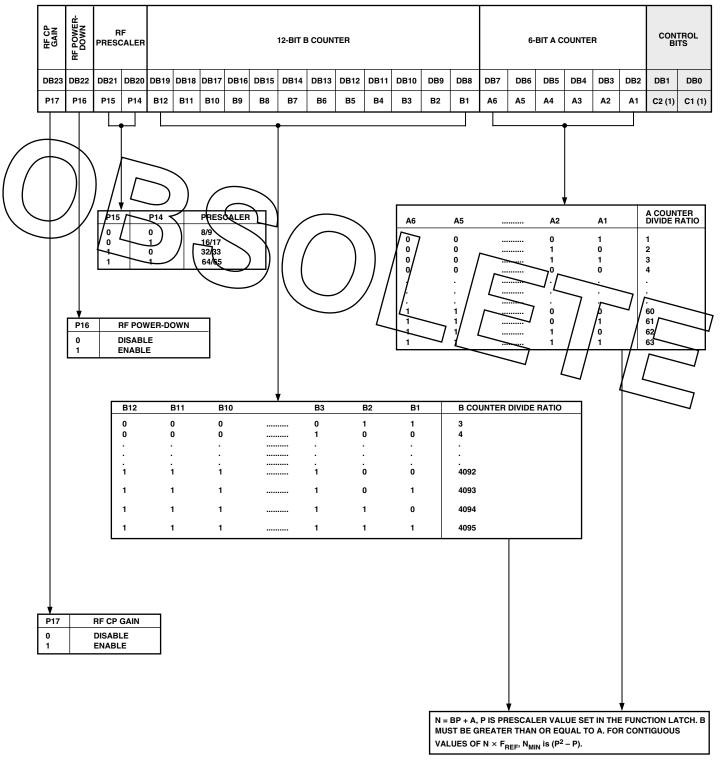


Table VI. RF N Counter Latch Map

RF N COUNTER LATCH



REV. A -15-

PROGRAM MODES

Table III and Table V show how to set up the Program Modes in the ADF421x family. The following should be noted:

- IF and RF Analog Lock Detect indicate when the PLL is in lock. When the loop is locked and either IF or RF Analog Lock Detect is selected, the MUXOUT pin will show a logic high with narrow low-going pulses. When the IF/RF Analog Lock Detect is chosen, the locked condition is indicated only when both IF and RF loops are locked.
- The IF Counter Reset mode resets the R and AB counters in the IF section and also puts the IF charge pump into three-state. The RF Counter Reset mode resets the R and AB counters in the RF section and also puts the RF charge pump into three-state. The IF and RF Counter Reset mode does both of the above. Upon removal of the reset bits, the AB counter resumer counting in close alignment with the R counter (maximum error is one prescaler output cycle).
 The Fastlock mode uses MUXOUT to switch a second loop filter damping resistor to ground during Fastlock operation. Activation of Fastlock occurs whenever RF CP Gain in the

IF Power-Down

It is possible to program the ADF421x family for either synchronous or asynchronous power-down on either the IF or RF side.

Synchronous IF Power-Down

RF Reference counter is set to one.

Programming a "1" to P7 of the ADF421x family will initiate a power-down. If P2 of the ADF421x family has been set to "0" (normal operation), a synchronous power-down is conducted. The device will automatically put the charge pump into three-state and then complete the power-down.

Asynchronous IF Power-Down

If P2 of the ADF421x family has been set to "1" (three-state the IF charge pump), and P7 is subsequently set to "1," an asynchronous power-down is conducted. The device will go into power-down on the rising edge of LE, which latches the "1" to the IF power-down bit (P7).

Synchronous RF Power-Down

Programming a "1" to P16 of the ADF421x family will initiate a power-down. If P10 of the ADF421x family has been set to "0" (normal operation), a synchronous power-down is conducted. The device will automatically put the charge pump into three-state and then complete the power-down.

Asynchronous RF Power-Down

If P10 of the ADF421x family has been set to "1" (three-state the RF charge pump), and P16 is subsequently set to "1," an asynchronous power-down is conducted. The device will go into power down on the rising edge of LE, which latches the "1" to the RF power-down bit (P16).

Activation of either synchronous or asynchronous power-down forces the IF/RF loop's R and AB dividers to their load state conditions and the IF/RF input section is debiased to a high-impedance state.

The $REF_{\rm IN}$ oscillator circuit is only disabled if both the IF and RF power-downs are set.

The input register and latches remain active and are capable of loading and latching data during all the power-down modes.

The IF/RF section of the devices will return to normal powered up operation immediately upon LE latching a "0" to the appropriate power-down bit.

IF SECTION

PROGRAMMABLE IF REFERENCE (R) COUNTER

If control bits C2, C1 are 0, 0, the data is transferred from the input shift register to the 14-bit IFR counter. Table III shows the input shift register data format for the IFR counter and the divide ratios possible.

IF Phase Detector Polarity

P1 sets the IF Phase Detector Polarity. When the IF VCO characteristics are positive this should be set to "1." When they are negative it should be set to "0." See Table III.

IF Charge Pump Three-State

P2 puts the IF charge pump into three-state mode when programmed to a "1." It should be set to "0" for normal operation. See Table III.

IF PROGRAM MODES

Table III and Table V show how to set up the Program Modes in the ADF421x family.

IF Charge Pump Currents

FCP2, IFCP1, IFCP0 program current setting for the IF charge pump. See Table III.

PROGRAMMABLE IF AB COUNTER

If control bits C2, C1 are 0, 1, the data in the input register is used to program the IF AB counter. The N counter consists of a 6-bit swallow counter (A counter) and 12-bit programmable counter (B counter). Table IV shows the input register data format for programming the IF AB counter and the possible divide ratios.

IF Prescaler Value

P5 and P6 in the IF A, B Counter Latch sets the IF prescaler value. See Table IV.

IF Power-Down

Table III and Table V show the power-down bits in the ADF421x family.

IF Fastlock

The IF CP Gain bit (P8) of the IF N register in the ADF421x family is the Fastlock Enable Bit. Only when this is "1" is IF Fastlock enabled. When Fastlock is enabled, the IF CP current is set to its maximum value. Since the IF CP Gain bit is contained in the IF N Counter, only one write is needed to both program a new output frequency and also initiate Fastlock. To come out of Fastlock, the IF CP Gain bit on the IF N register must be set to "0." See Table IV.

RF SECTION

PROGRAMMABLE RF REFERENCE (R) COUNTER

If control bits C2, C1 are 1, 0, the data is transferred from the input shift register to the 14-bit RFR counter. Table V shows the input shift register data format for the RFR counter and the possible divide ratios.

RF Phase Detector Polarity

P9 sets the IF Phase Detector Polarity. When the RF VCO characteristics are positive this should be set to "1." When they are negative it should be set to "0." See Table V.

RF Charge Pump Three-State

P10 puts the RF charge pump into three-state mode when programmed to a "1." It should be set to "0" for normal operation. See Table V.

RF PROGRAM MODES

Table III and Table V show how to set up the Program Modes in the ADF421x family.

RF Charge Pump Currents

RFCP2, RFCP1, RFCP0 program current setting for the RF charge pump. See Table V.

PROGRAMMABLE RF N COUNTER

If control bits C2, C1 are 1, 1, the data in the input register is used to program the RF N (A + B) counter. The N counter consists of a 6-bit swallow counter (A Counter) and 12-bit programmable counter (B Counter). Table IV shows the input register data format for programming the RF N counter and the possible divide ratios.

RF Presealer Value

Pl4 and Pl5 in the RFA, B Counter Latch sets the RF pres-

caler value. See Table VI.

Table III and Table V show the power-down bits in the ADF421x family.

RF Fastlock

The RF CP Gain bit (P17) of the RF N register in the ADF421x family is the Fastlock Enable Bit. Only when this is "1" is IF Fastlock enabled. When Fastlock is enabled, the RF CP current is set to its maximum value. Also an extra loop filter damping resistor to ground is switched in using the FL₀ pin, thus compensating for the change in loop characteristics while in Fastlock. Since the RF CP Gain bit is contained in the RF N Counter, only one write is needed to both program a new output frequency and also initiate Fastlock. To come out of Fastlock, the RF CP Gain bit on the RF N register must be set to "0." See Table VI.

APPLICATIONS SECTION

Local Oscillator for GSM Handset Receiver

Figure 7 shows the ADF4210/ADF4211/ADF4212/ADF4213 being used with a VCO to produce the LO for a GSM base station transmitter.

The reference input signal is applied to the circuit at FREF_{IN} and, in this case, is terminated in 50 Ω . A typical GSM system would have a 13 MHz TCXO driving the reference input without any 50 Ω termination. In order to have a channel spacing of 200 kHz (the GSM standard), the reference input must be divided by 65, using the on-chip reference.

WIDEBAND PLL

Many of the wireless applications for synthesizers and VCOs in PLLs are narrowband in nature. These applications include various wireless standards such as GSM, DSC1800, CDMA, or WCDMA. In each of these cases, the total tuning range for the local oscillator is less than 100 MHz. However, there are also wideband applications where the local oscillator could have up to an octave tuning range. For example, cable TV tuners have a total range of about 400 MHz. Figure 8 shows an application where the ADF4213 is used to control and program the Micronetics M3500–1324. The loop filter was designed for an RF output of 2100 MHz, a loop handwidth of 40 kHz, a PFD requency of 1 MHz, I_{CP} of 10 mA (2.5 mA synthesizer I_{CP} multiplied by the gain factor of 4), VCO K_D of 80 MHz/V (sensitivity of the M3500–1324 at an output of 2100 MHz) and a phase margin of 45°C.

In narrowband applications, there is generally a small variation (less than 10%) in output frequency and also a small variation (typically < 10%) in VCO sensitivity over the range. However,

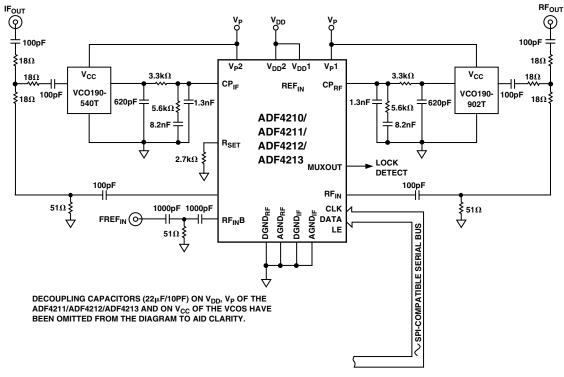
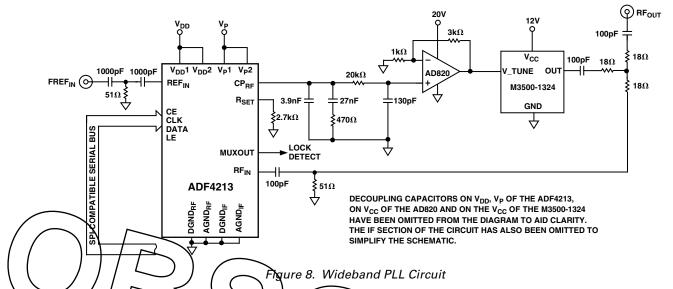


Figure 7. GSM Handset Receiver Local Oscillator Using the ADF4210/ADF4211/ADF4212/ADF4213



in wide-band applications both of these parameters have a much greater variation. In Figure 8, for example, we have -25% and +30% variation in the RF output from the nominal 18 GHz. The sensitivity of the VCO can vary from 130 MHz/V at 1900 MHz to 30 MHz/V at 2400 MHz. Variations in these parameters will change the loop bandwidth. This in turn can affect stability and lock time. By changing the programmable $I_{\rm CP}$, it is possible to obtain compensation for these varying loop conditions and ensure that the loop is always operating close to optimal conditions.

INTERFACING

The ADF4210/ADF4211/ADF4212/ADF4213 family has a simple SPI-compatible serial interface for writing to the device. SCLK, SDATA, and LE control the data transfer. When LE (Latch Enable) goes high, the 22 bits that have been clocked into the input register on each rising edge of SCLK will be transferred to the appropriate latch. See Figure 1 for the Timing Diagram and Table I for the Latch Truth Table.

The maximum allowable serial clock rate is 20 MHz. This means that the maximum update rate possible for the device is 909 kHz, or one update every 1.1 ms. This is certainly more than adequate for systems that will have typical lock times in hundreds of microseconds.

ADuC812 to ADF421x Family Interface

Figure 9 shows the interface between the ADF421x family and the ADuC812 microconverter. Since the ADuC812 is based on an 8051 core, this interface can be used with any 8051-based microcontroller. The microconverter is set up for SPI Master Mode with CPHA = 0. To initiate the operation, the I/O port driving LE is brought low. Each latch of the ADF421x family needs a 24-bit word. This is accomplished by writing three 8-bit bytes from the microconverter to the device. When the third byte has been written, the LE input should be brought high to complete the transfer.

On first applying power to the ADF421x family, it needs four writes (one each to the R counter latch and the AB counter latch for both RF1 and RF2 sides) for the output to become active.

When operating in the mode described, the maximum SCLOCK rate of the ADuC812 is 4 MHz. This means that the maximum rate at which the output frequency can be changed will be about

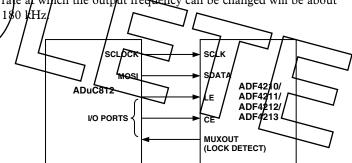


Figure 9. ADuC812 to ADF421x Family Interface

ADSP-21xx to ADF421x Family Interface

Figure 10 shows the interface between the ADF421x family and the ADSP-21xx Digital Signal Processor. As previously discussed, the ADF421x family needs a 24-bit serial word for each latch write. The easiest way to accomplish this, using the ADSP-21xx family, is to use the Autobuffered Transmit Mode of operation with Alternate Framing. This provides a means for transmitting an entire block of serial data before an interrupt is generated. Set up the word length for eight bits and use three memory locations for each 24-bit word. To program each 24-bit latch, store the three 8-bit bytes, enable the Autobuffered mode, and write to the transmit register of the DSP. This last operation initiates the autobuffer transfer.

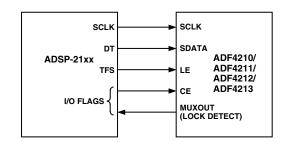


Figure 10. ADSP-21xx to ADF421x Family Interface

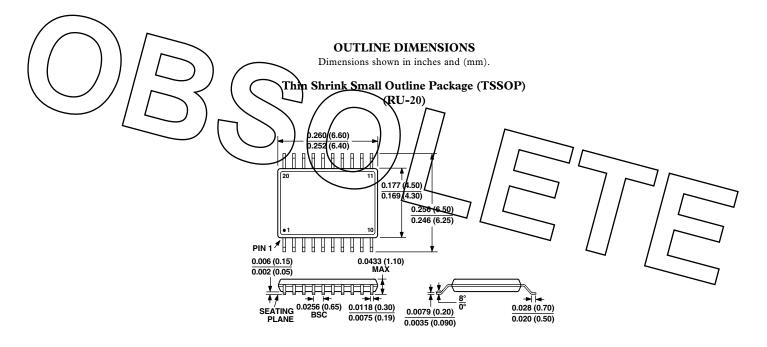
–18– REV. A

PCB Guidelines for Chip Scale Package

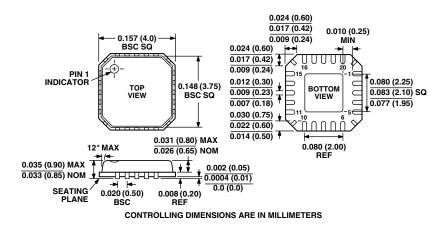
The lands on the chip scale package (CP-20), are rectangular. The printed circuit board pad for these should be 0.1 mm longer than the package land length and 0.05 mm wider than the package land width. The land should be centered on the pad. This will ensure that the solder joint size is maximized.

The bottom of the chip scale package has a central thermal pad. The thermal pad on the printed circuit board should be at least as large as this exposed pad. On the printed circuit board, there should be clearance of at least 0.25 mm between the thermal pad and inner edges of the pad pattern. This will ensure that shorting is avoided.

Thermal vias may be used on the printed circuit board thermal pad to improve thermal performance of the package. If vias are used, they should be incorporated in the thermal pad at 1.2 mm grid pitch. The via diameter should be between 0.3 mm and 0.33 mm and the via barrel should be plated with 1 oz. copper to plug the via. The user should connect the printed circuit board pad to AGND.



Chip Scale Package (CP-20)



REV. A -19-

ADF4210/ADF4211/ADF4212/ADF4213—Revision History

| Location | Page |
|---|------|
| Data Sheet changed from REV. 0 to REV. A. | |
| Changes to Test Conditions/Comments section of Specifications | 2 |
| Edit to RF _{IN} and IF _{IN} Function text | 5 |
| PCB Guidelines for Chip Scale Package section added | 19 |
| CP-20 Package replaced by CP-20[2] | 19 |

